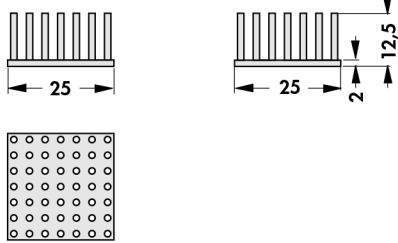
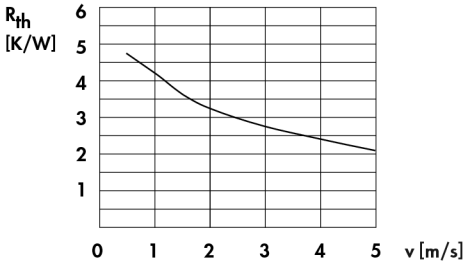
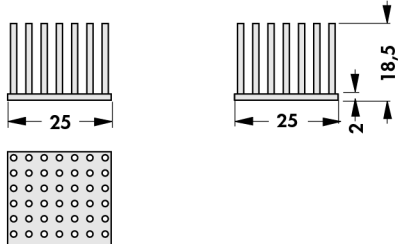
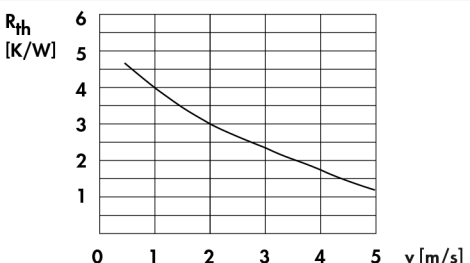
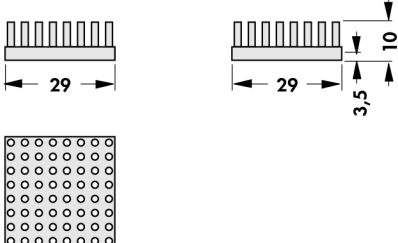
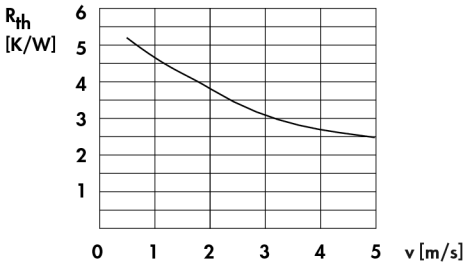
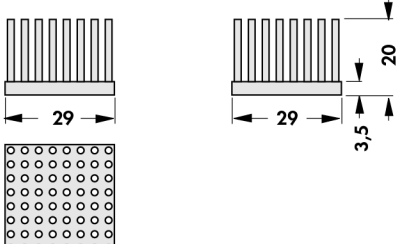
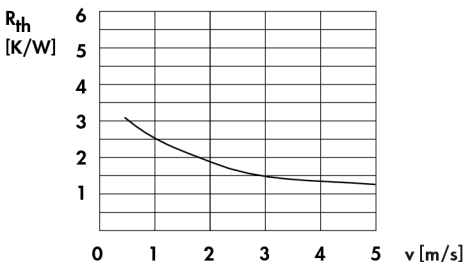
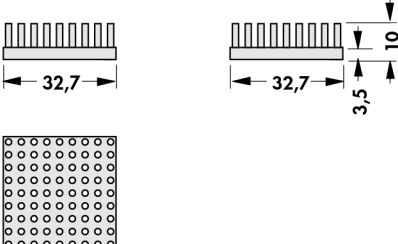
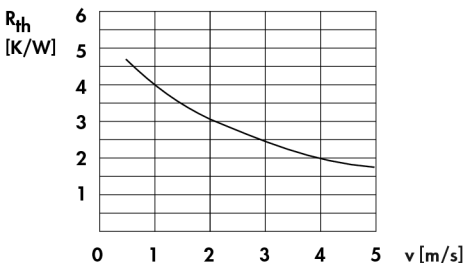
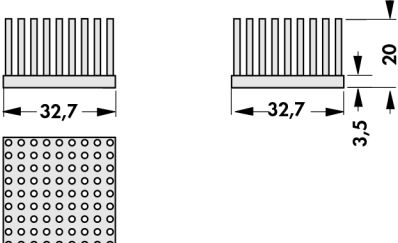
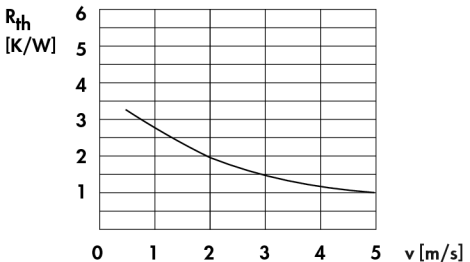


## Pin heatsinks

|   |   |  |
|---|---|--|
| <p><b>art. no.</b></p> <p><b>ICK S 25 x 25 x 12,5</b><br/>WLF ... 25 x 25<br/>weight: 6 g</p> |    |    |
| <p><b>art. no.</b></p> <p><b>ICK S 25 x 25 x 18,5</b><br/>WLF ... 25 x 25<br/>weight: 7 g</p> |    |    |
| <p><b>art. no.</b></p> <p><b>ICK S 29 x 29 x 10</b><br/>WLF ... 29 x 29<br/>weight: 11 g</p>  |   |   |
| <p><b>art. no.</b></p> <p><b>ICK S 29 x 29 x 20</b><br/>WLF ... 29 x 29<br/>weight: 15 g</p>  |  |  |
| <p><b>art. no.</b></p> <p><b>ICK S 32 x 32 x 10</b><br/>WLF ... 32 x 32<br/>weight: 14 g</p>  |  |  |
| <p><b>art. no.</b></p> <p><b>ICK S 32 x 32 x 20</b><br/>WLF ... 32 x 32<br/>weight: 19 g</p>  |  |  |

Thermal conduct. foil WLF 404/405 → E 5  
 Thermal conductive glue → E 14  
 Thermal conductive paste → E 12  
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27  
 Mounting material for semiconduct. → E 34 - 38  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7